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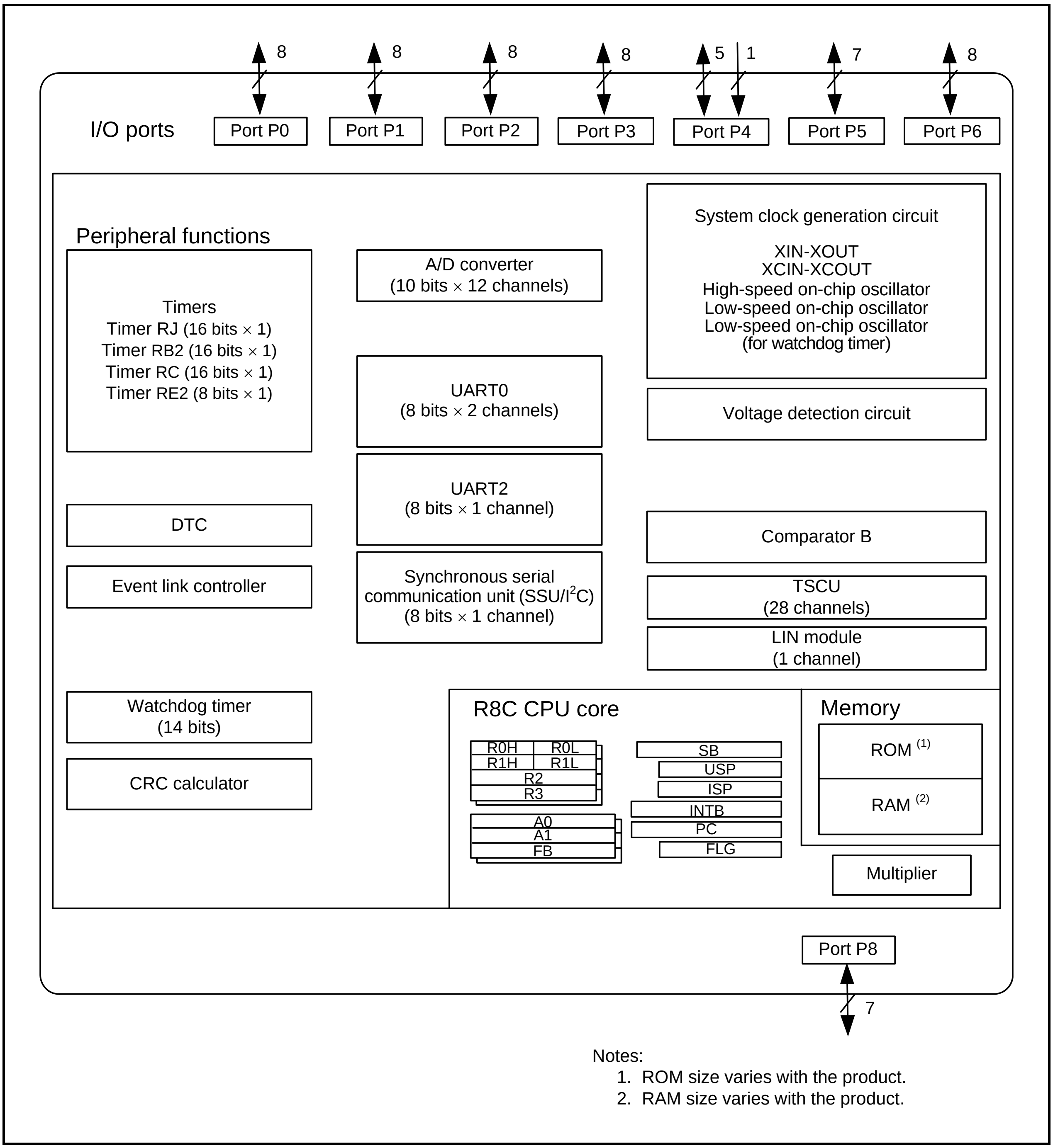
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	59
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21368sdfp-30

1.3 Block Diagram

Figure 1.2 shows the Block Diagram.



Notes:
1. ROM size varies with the product.
2. RAM size varies with the product.

Figure 1.2 Block Diagram

1.5 Pin Functions

Tables 1.7 and 1.8 list Pin Functions.

Table 1.7 Pin Functions (1)

Item	Pin Name	I/O	Description
Power supply input	VCC, VSS	—	Apply 1.8 V through 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	—	Power supply input for the A/D converter. Connect a capacitor between pins AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Applying a low level to this pin resets the MCU.
MODE	MODE	I	Connect this pin to the VCC pin via a resistor.
XIN clock input	XIN	I	I/O for the XIN clock generation circuit. Connect a ceramic resonator or a crystal oscillator between pins XIN and XOUT. (1) To use an external clock, input it to the XIN pin and leave the XOUT pin open.
XIN clock output	XOUT	I/O	
XCIN clock input	XCIN	I	I/O for the XCIN clock generation circuit. Connect a crystal oscillator between pins XCIN and XCOUT. (1) To use an external clock, input it to the XCOUT pin and leave the XCIN pin open.
XCIN clock output	XCOUT	I/O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT4}}$	I	$\overline{\text{INT}}$ interrupt input.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input.
Timer RJ_0	TRJIO_0	I/O	Input/output for timer RJ.
	TRJO_0	O	Output for timer RJ.
Timer RB2_0	TRBO_0	O	Output for timer RB2.
Timer RC_0	TRCCLK_0	I	External clock input.
	TRCTRG_0	I	External trigger input.
	TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0	I/O	Input/output for timer RC.
Timer RE2	TMRE2O	O	Divided clock output.
Serial interface (UART0)	CLK_0, CLK_1	I/O	Transfer clock input/output.
	RXD_0, RXD_1	I	Serial data input.
	TXD_0, TXD_1	O	Serial data output.
Serial interface (UART2)	$\overline{\text{CTS2}}$	I	Input for transmission control.
	$\overline{\text{RTS2}}$	O	Output for reception control.
	SCL2	I/O	I^{2}C mode clock input/output.
	SDA2	I/O	I^{2}C mode data input/output.
	RXD2	I	Serial data input.
	TXD2	O	Serial data output.
	CLK2	I/O	Transfer clock input/output.
Synchronous serial communication unit (SSU_0)	SSI_0	I/O	Data input/output.
	$\overline{\text{SCS\_0}}$	I/O	Chip-select input/output.
	$\overline{\text{SSCK\_0}}$	I/O	Clock input/output.
	SSO_0	I/O	Data input/output.
I^{2}C bus (I^{2}C_0)	SCL_0	I/O	Clock input/output.
	SDA_0	I/O	Data input/output.
Reference voltage input	VREF	I	Reference voltage input for the A/D converter.

Note:

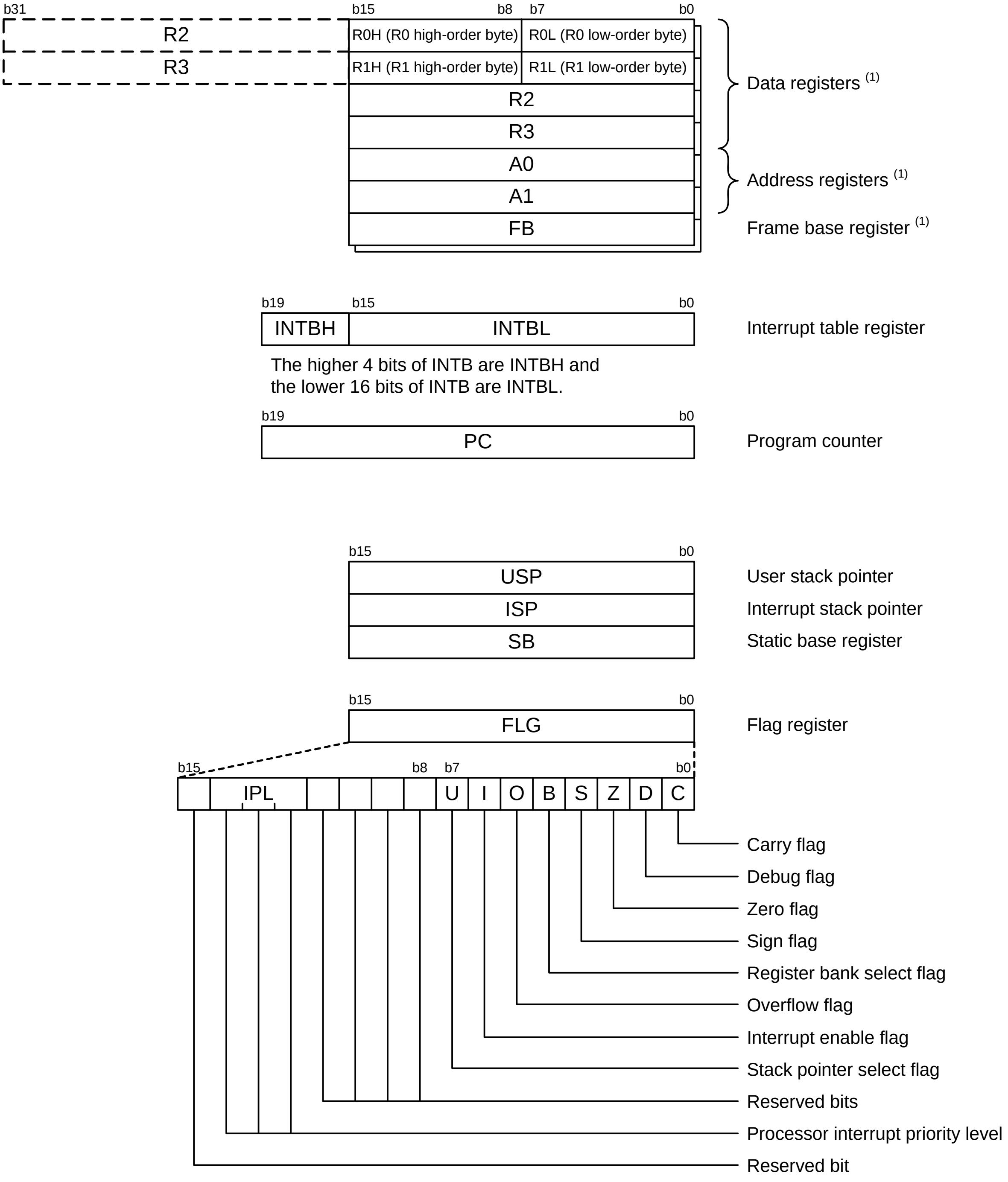
1. Contact the oscillator manufacturer for oscillation characteristics.

Table 1.8 Pin Functions (2)

Item	Pin Name	I/O	Description
A/D converter	AN0 to AN11	I	Analog input for the A/D converter.
	$\overline{\text{ADTRG}}$	I	External trigger input for the A/D converter.
Comparator B	IVCMP1, IVCMP3	I	Analog voltage input for comparator B.
	IVREF1, IVREF3	I	Reference voltage input for comparator B.
Touch sensor control unit	CHxA0, CHxA1, CHxB, CHxC	I/O	Control pins for electrostatic capacitive touch detection.
	CH00 to CH08, CH10, CH11, CH16 to CH25, CH27, CH28, CH31 to CH35	I	Electrostatic capacitive touch detection pins.
I/O ports	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_3 to P4_7, P5_0 to P5_4, P5_6, P5_7, P6_0 to P6_7, P8_0 to P8_6	I/O	8-bit CMOS input/output ports. Each port has an I/O select direction register, enabling switching input and output for each pin. For input ports, the presence or absence of a pull-up resistor can be selected by a program. All ports can be used as LED drive (high drive) ports.
Input port	P4_2	I	Input-only port.

2. Central Processing Unit (CPU)

Figure 2.1 shows the 13 CPU Registers. The registers R0, R1, R2, R3, A0, A1, and FB form a single register bank. The CPU has two register banks.



Note:
1. These registers form a single register bank.
The CPU has two register banks.

Figure 2.1 CPU Registers

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts. Interrupts are disabled when the I flag is 0, and are enabled when the I flag is 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is 0. USP is selected when the U flag is 1. The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction for a software interrupt numbered from 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns eight processor interrupt priority levels from 0 to 7. If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

The write value must be 0. The read value is undefined.

Table 3.3 SFR Information (3) (1)

Address	Symbol	Register Name	After Reset	Remarks
0007Ah				
0007Bh				
0007Ch				
0007Dh				
0007Eh				
0007Fh				
00080h	U0MR_0	UART0_0 Transmit/Receive Mode Register	00h	
00081h	U0BRG_0	UART0_0 Bit Rate Register	XXh	
00082h	U0TB_0	UART0_0 Transmit Buffer Register	XXh	
00083h			XXh	
00084h	U0C0_0	UART0_0 Transmit/Receive Control Register 0	00001000b	
00085h	U0C1_0	UART0_0 Transmit/Receive Control Register 1	00000010b	
00086h	U0RB_0	UART0_0 Receive Buffer Register	XXXXh	
00087h				
00088h	U0IR_0	UART0_0 Interrupt Flag and Enable Register	00h	
00089h				
0008Ah				
0008Bh				
0008Ch	LINCR2_0	LIN_0 Special Function Register	00h	
0008Dh				
0008Eh	LINCT_0	LIN_0 Control Register	00h	
0008Fh	LINST_0	LIN_0 Status Register	00h	
00090h	U0MR_1	UART0_1 Transmit/Receive Mode Register	00h	
00091h	U0BRG_1	UART0_1 Bit Rate Register	XXh	
00092h	U0TB_1	UART0_1 Transmit Buffer Register	XXh	
00093h			XXh	
00094h	U0C0_1	UART0_1 Transmit/Receive Control Register 0	00001000b	
00095h	U0C1_1	UART0_1 Transmit/Receive Control Register 1	00000010b	
00096h	U0RB_1	UART0_1 Receive Buffer Register	XXXXh	
00097h				
00098h	U0IR_1	UART0_1 Interrupt Flag and Enable Register	00h	
00099h				
0009Ah				
0009Bh				
0009Ch				
0009Dh				
0009Eh				
0009Fh				
000A0h				
000A1h				
000A2h				
000A3h				
000A4h				
000A5h				
000A8h				
000A9h				
000AAh				
000ABh				
000ACh				
000ADh				
000AEh				
000AFh				
000B0h				
000B1h				
000B4h				
000B5h				
000B8h				
000B9h				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.9 SFR Information (9) (1)

Address	Symbol	Register Name	After Reset	Remarks
00280h	DTCTL	DTC Activation Control Register	00h	
00281h				
00282h				
00283h				
00284h				
00285h				
00286h				
00287h				
00288h	DTCEN0	DTC Activation Enable Register 0	00h	
00289h	DTCEN1	DTC Activation Enable Register 1	00h	
0028Ah	DTCEN2	DTC Activation Enable Register 2	00h	
0028Bh	DTCEN3	DTC Activation Enable Register 3	00h	
0028Ch				
0028Dh	DTCEN5	DTC Activation Enable Register 5	00h	
0028Eh	DTCEN6	DTC Activation Enable Register 6	00h	
0028Fh				
00290h	CRCSAR	SFR Snoop Address Register	0000h	
00291h				
00292h	CRCMR	CRC Control Register	00h	
00293h				
00294h	CRCD	CRC Data Register	0000h	
00295h				
00296h	CRCIN	CRC Input Register	00h	
00297h				
00298h				
00299h				
0029Ah				
0029Bh				
0029Ch				
0029Dh				
0029Eh				
0029Fh				
002A0h	TRJ_0SR	Timer RJ_0 Pin Select Register	08h	
002A1h				
002A2h				
002A3h				
002A4h				
002A5h	TRCCLKSR	Timer RCCLK Pin Select Register	00h	
002A6h	TRC_0SR0	Timer RC_0 Pin Select Register 0	00h	
002A7h	TRC_0SR1	Timer RC_0 Pin Select Register 1	00h	
002A8h				
002A9h				
002AAh				
002ABh				
002ACh				
002ADh	TIMSR	Timer Pin Select Register	00h	
002AEh	U_0SR	UART0_0 Pin Select Register	00h	
002AFh	U_1SR	UART0_1 Pin Select Register	00h	
002B0h				
002B1h				
002B2h	U2SR0	UART2 Pin Select Register 0	00h	
002B3h	U2SR1	UART2 Pin Select Register 1	00h	
002B4h				
002B5h				
002B6h	INTSR0	INT Interrupt Input Pin Select Register 0	00h	
002B7h				
002B8h				
002B9h	PINSR	I/O Function Pin Select Register	00h	
002BAh				
002BBh				
002BCh				
002BDh				
002BEh	PMCSEL	Pin Assignment Select Register	00h	
002BFh				

Note:
1. The blank areas are reserved. No access is allowed.

Table 3.13 SFR Information (13) (1)

Address	Symbol	Register Name	After Reset	Remarks
06C0Ah		Area for storing DTC transfer vector 10	XXh	
06C0Bh		Area for storing DTC transfer vector 11	XXh	
06C0Ch		Area for storing DTC transfer vector 12	XXh	
06C0Dh		Area for storing DTC transfer vector 13	XXh	
06C0Eh		Area for storing DTC transfer vector 14	XXh	
06C0Fh		Area for storing DTC transfer vector 15	XXh	
06C10h		Area for storing DTC transfer vector 16	XXh	
06C11h		Area for storing DTC transfer vector 17	XXh	
06C12h		Area for storing DTC transfer vector 18	XXh	
06C13h		Area for storing DTC transfer vector 19	XXh	
06C14h				
06C15h				
06C16h		Area for storing DTC transfer vector 22	XXh	
06C17h		Area for storing DTC transfer vector 23	XXh	
06C18h		Area for storing DTC transfer vector 24	XXh	
06C19h		Area for storing DTC transfer vector 25	XXh	
06C1Ah				
06C1Bh				
06C1Ch				
06C1Dh				
06C1Eh				
06C1Fh				
06C20h				
06C21h				
06C22h				
06C23h				
06C24h				
06C25h				
06C26h				
06C27h				
06C28h				
06C29h				
06C2Ah		Area for storing DTC transfer vector 42	XXh	
06C2Bh				
06C2Ch				
06C2Dh				
06C2Eh				
06C2Fh				
06C30h				
06C31h		Area for storing DTC transfer vector 49	XXh	
06C32h				
06C33h		Area for storing DTC transfer vector 51	XXh	
06C34h		Area for storing DTC transfer vector 52	XXh	
06C35h		Area for storing DTC transfer vector 53	XXh	
06C36h		Area for storing DTC transfer vector 54	XXh	
06C37h				
06C38h				
06C39h				
06C3Ah				
06C3Bh				
06C3Ch				
06C3Dh				
06C3Eh				
06C3Fh				
06C40h	DTCCR0	DTC Control Register 0	XXh	
06C41h	DTBLS0	DTC Block Size Register 0	XXh	
06C42h	DTCCT0	DTC Transfer Count Register 0	XXh	
06C43h	DTRLD0	DTC Transfer Count Reload Register 0	XXh	
06C44h	DTSAR0	DTC Source Address Register 0	XXXXh	
06C45h				
06C46h	DTDAR0	DTC Destination Address Register 0	XXXXh	
06C47h				
06C48h	DTCCR1	DTC Control Register 1	XXh	
06C49h	DTBLS1	DTC Block Size Register 1	XXh	

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

Table 3.17 ID code Area, Option Function Select Area

Address	Symbol	Area Name	After Reset	Address size
:				
0FFDBh	OFS2	Option Function Select Register 2	(Note 1)	
:				
0FFDFh	ID1		(Note 2)	
:				
0FFE3h	ID2		(Note 2)	
:				
0FFEBh	ID3		(Note 2)	
:				
0FFEFh	ID4		(Note 2)	
:				
0FFF3h	ID5		(Note 2)	
:				
0FFF7h	ID6		(Note 2)	
:				
0FFFBh	ID7		(Note 2)	
:				
0FFFFh	OFS	Option Function Select Register	(Note 1)	

Notes:

1. The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program.
   Do not perform any additional writes to the option function select area. Erasing the block including the option function select area sets the option function select area to FFh.
2. The ID code area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program. Do not perform any additional writes to the ID code area. Erasing the block including the ID code area sets the ID code area to FFh.

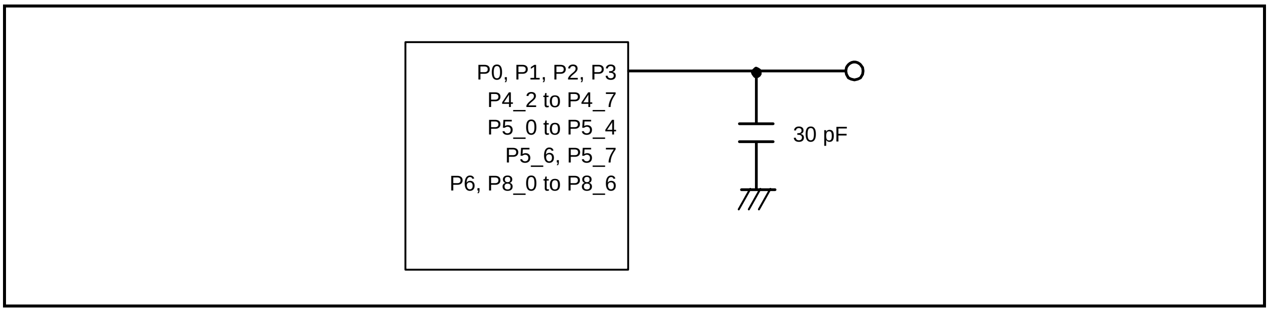


Figure 4.1 **Timing Measurement Circuit for Ports P0, P1, P2, P3, P4_2 to P4_7, P5_0 to P5_4, P5_6, P5_7, P6, and P8_0 to P8_6**

Table 4.8 Voltage Detection 1 Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{det1}	Voltage detection level Vdet1_0 (1)	When Vcc falls	2.00	2.20	2.40	V
	Voltage detection level Vdet1_1 (1)	When Vcc falls	2.15	2.35	2.55	V
	Voltage detection level Vdet1_2 (1)	When Vcc falls	2.30	2.50	2.70	V
	Voltage detection level Vdet1_3 (1)	When Vcc falls	2.45	2.65	2.85	V
	Voltage detection level Vdet1_4 (1)	When Vcc falls	2.60	2.80	3.00	V
	Voltage detection level Vdet1_5 (1)	When Vcc falls	2.75	2.95	3.15	V
	Voltage detection level Vdet1_6 (1)	When Vcc falls	2.80	3.10	3.40	V
	Voltage detection level Vdet1_7 (1)	When Vcc falls	2.95	3.25	3.55	V
	Voltage detection level Vdet1_8 (1)	When Vcc falls	3.10	3.40	3.70	V
	Voltage detection level Vdet1_9 (1)	When Vcc falls	3.25	3.55	3.85	V
	Voltage detection level Vdet1_A (1)	When Vcc falls	3.40	3.70	4.00	V
	Voltage detection level Vdet1_B (1)	When Vcc falls	3.55	3.85	4.15	V
	Voltage detection level Vdet1_C (1)	When Vcc falls	3.70	4.00	4.30	V
	Voltage detection level Vdet1_D (1)	When Vcc falls	3.85	4.15	4.45	V
	Voltage detection level Vdet1_E (1)	When Vcc falls	4.00	4.30	4.60	V
	Voltage detection level Vdet1_F (1)	When Vcc falls	4.15	4.45	4.75	V
—	Hysteresis width at the rising of Vcc in voltage detection 1 circuit	Vdet1_0 to Vdet1_5 selected	—	0.07	—	V
		Vdet1_6 to Vdet1_F selected	—	0.10	—	V
—	Voltage detection 1 circuit response time (2)	At the falling of Vcc from 5 V to (Vdet1 – 0.1) V	—	60	150	µs
—	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (3)		—	—	100	µs

Notes:

1. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
2. Time until the voltage monitor 1 interrupt request is generated after the voltage passes V_{det1}.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 4.9 Voltage Detection 2 Circuit Characteristics (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V_{det2}	Voltage detection level Vdet2_0	When Vcc falls	3.70	4.00	4.30	V
—	Hysteresis width at the rising of Vcc in voltage detection 2 circuit		—	0.1	—	µs
—	Voltage detection 2 circuit response time (1)	At the falling of Vcc from 5 V to (Vdet2_0 – 0.1) V	—	20	150	µs
—	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (2)		—	—	100	µs

Notes:

1. Time until the voltage monitor 2 interrupt request is generated after the voltage passes V_{det2}.
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 4.16 DC Characteristics (3) [2.7 V ≤ Vcc < 4.2 V] (Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output high voltage	Other than XOUT	Drive capacity is high	I_{OH} = –5 mA	Vcc – 0.5	—	Vcc	V
			Drive capacity is low	I_{OH} = –1 mA	Vcc – 0.5	—	Vcc	V
		XOUT		I_{OH} = –200 µA	1.0	—	Vcc	V
V_{OL}	Output low voltage	Other than XOUT	Drive capacity is high	I_{OL} = 5 mA	—	—	0.5	V
			Drive capacity is low	I_{OL} = 1 mA	—	—	0.5	V
		XOUT		I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{\mathrm{INT0}}$ to $\overline{\mathrm{INT4}}$, $\overline{\mathrm{KI0}}$ to $\overline{\mathrm{KI3}}$, TRJIO_0, TRCCLK_0, TRCTRG_0, TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0, CLK_0, CLK_1, RXD_0, RXD_1, $\overline{\mathrm{CTS2}}$, SCL2, SDA2, CLK2, RXD2, SCL_0, SDA_0, SSI_0, $\overline{\mathrm{SCS\_0}}$, SSCK_0, SSO_0			0.1	0.4	—	V
		$\overline{\mathrm{RESET}}$	Vcc = 3.0 V		0.1	0.5	—	V
I_{IH}	Input high current		V_I = 3.0 V		—	—	1.0	µA
I_{IL}	Input low current		V_I = 0 V		—	—	–1.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V		42	84	168	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Table 4.19 DC Characteristics (6) [1.8 V ≤ Vcc < 2.7 V] (Topr = −20°C to 85°C (N version)/−40°C to 85°C (D version), unless otherwise specified)

Symbol	Parameter	Conditions								Standard (4)			Unit
			Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.	
			XIN (2)	XCIN	High-Speed	Low-Speed							
Icc	Power supply current (1)	High-speed clock mode	5 MHz	Off	Off	125 kHz	No division	—		—	2.2	—	mA
			5 MHz	Off	Off	125 kHz	Divide-by-8	—		—	0.8	—	mA
		High-speed on-chip oscillator mode	Off	Off	5 MHz (3)	125 kHz	No division	—		—	2.5	10	mA
			Off	Off	5 MHz (3)	125 kHz	Divide-by-8	—		—	1.7	—	mA
			Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1		—	1	—	mA
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0		—	90	300	μA
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 SVC0 = 0		—	80	350	μA
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	μA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	80	μA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	μA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6	μA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	μA

Notes:

1. Vcc = 1.8 V to 2.7 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.
   The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

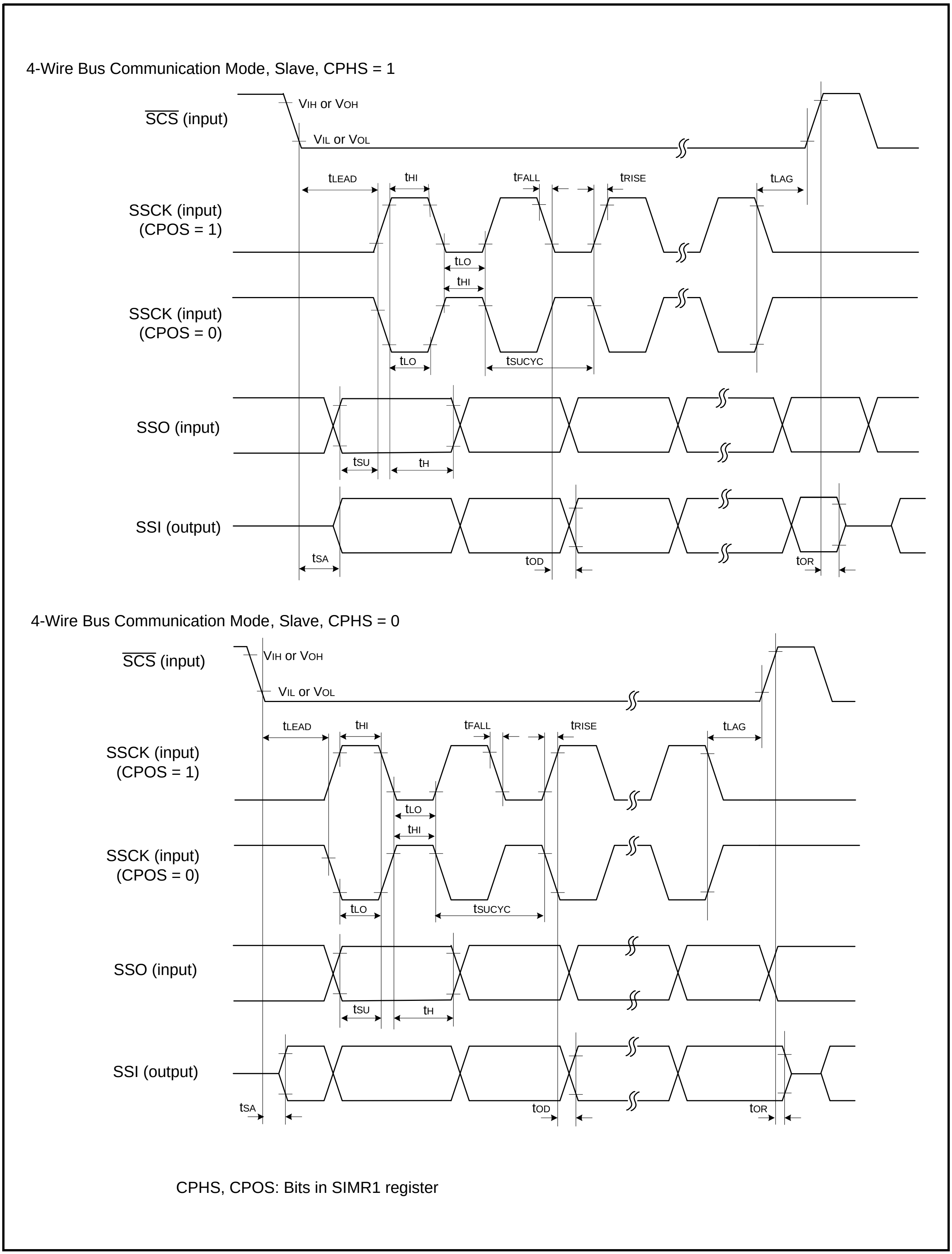
4.5 AC Characteristics

Table 4.20 Timing Requirements of Clock Synchronous Serial I/O with Chip Select (during Master Operation)
(Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = –20°C to 85°C (N version)/ –40°C to 85°C (D version))

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
t_{SUCYC}	SSCK clock cycle time		4.00	—	—	t_{CYC} (1)
t_{HI}	SSCK clock high width		0.40	—	0.60	t_{SUCYC}
t_{LO}	SSCK clock low width		0.40	—	0.60	t_{SUCYC}
t_{RISE}	SSCK clock rising time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	0.50	t_{CYC} (1)
		1.8 V ≤ Vcc < 2.7 V	—	—	1.00	t_{CYC} (1)
t_{FALL}	SSCK clock falling time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	0.50	t_{CYC} (1)
		1.8 V ≤ Vcc < 2.7 V	—	—	1.00	t_{CYC} (1)
t_{SU}	SSI, SSO data input setup time	4.5 V ≤ Vcc ≤ 5.5 V	60	—	—	ns
		2.7 V ≤ Vcc < 4.5 V	70	—	—	ns
		1.8 V ≤ Vcc < 2.7 V	100	—	—	ns
t_H	SSI, SSO data input hold time	2.7 V ≤ Vcc ≤ 5.5 V	2.00	—	—	t_{CYC} (1)
		1.8 V ≤ Vcc < 2.7 V	2.00	—	—	t_{CYC} (1)
t_{LEAD}	$\overline{SCS}$-SCK output delay time		0.5 t_{SUCYC} - 1 t_{CYC}	—	—	ns
t_{LAG}	SCK -$\overline{SCS}$ output valid time		0.5 t_{SUCYC} - 1 t_{CYC}	—	—	ns
t_{OD}	SSO data output delay time	2.7 V ≤ Vcc ≤ 5.5 V	—	—	30.00	ns
		1.8 V ≤ Vcc < 2.7 V	—	—	1.00	t_{CYC} (1)

Note:

1. $1t_{CYC} = 1/f1$ (s)



4-Wire Bus Communication Mode, Slave, CPHS = 1

4-Wire Bus Communication Mode, Slave, CPHS = 0

CPHS, CPOS: Bits in SIMR1 register

Figure 4.5 I/O Timing of Synchronous Serial Communication Unit (SSU) (Slave)

Table 4.22 External Clock Input (XOUT, XCIN)

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	200	—	50	—	50	—	ns
$t_{WH(XOUT)}$	XOUT input high width	90	—	24	—	24	—	ns
$t_{WL(XOUT)}$	XOUT input low width	90	—	24	—	24	—	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	—	14	—	14	—	µs
$t_{WH(XCIN)}$	XCIN input high width	7	—	7	—	7	—	µs
$t_{WL(XCIN)}$	XCIN input low width	7	—	7	—	7	—	µs

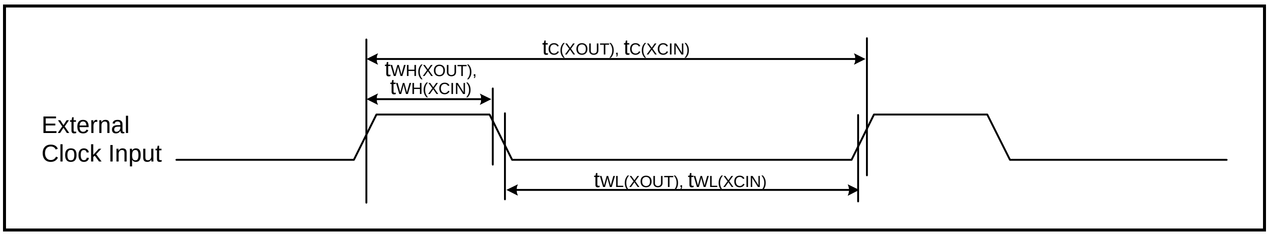


Figure 4.7 External Clock Input Timing Diagram

Table 4.23 Timing Requirements of TRJIO

Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{c(TRJIO)}$	TRJIO input cycle time	500	—	300	—	100	—	ns
$t_{WH(TRJIO)}$	TRJIO input high width	200	—	120	—	40	—	ns
$t_{WL(TRJIO)}$	TRJIO input low width	200	—	120	—	40	—	ns

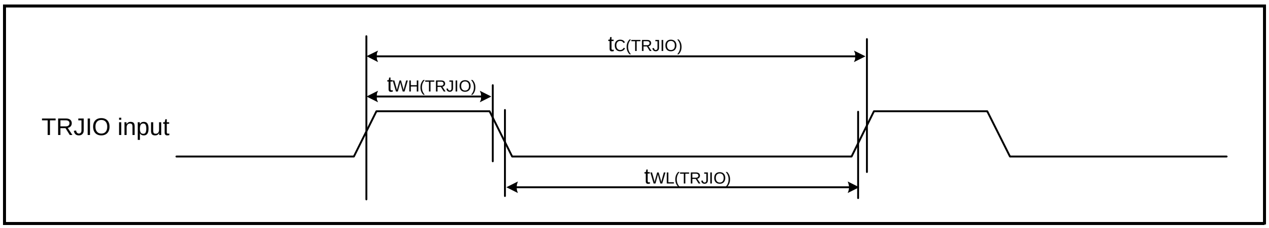


Figure 4.8 Input Timing of TRJIO

Table 4.26 Timing Requirements of External Interrupt $\overline{\text{INTi}}$ (i = 0 to 4) and Key Input Interrupt $\overline{\text{KIj}}$ (j = 0 to 3)

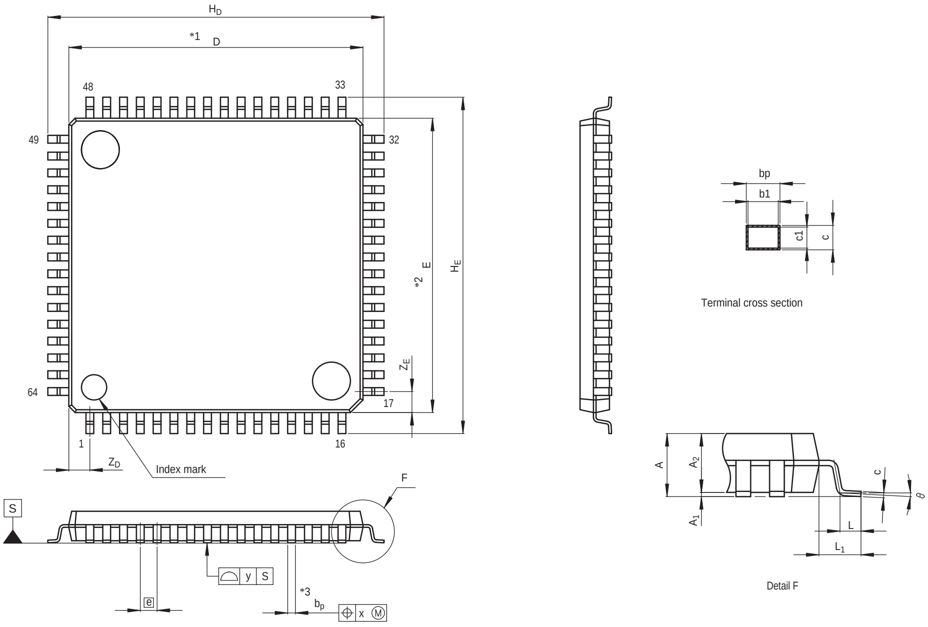
Symbol	Parameter	Standard						Unit
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C		
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{w(INH)}$	$\overline{\text{INTi}}$ input high width, $\overline{\text{KIj}}$ input high width	1000 (1)	—	380 (1)	—	250 (1)	—	ns
$t_{w(INL)}$	$\overline{\text{INTi}}$ input low width, $\overline{\text{KIj}}$ input low width	1000 (2)	—	380 (2)	—	250 (2)	—	ns

Notes:

1. When selecting the digital filter by the $\overline{\text{INTi}}$ input filter select bit, use an $\overline{\text{INTi}}$ input high pulse width of either (1/digital filter sampling frequency × 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{\text{INTi}}$ input filter select bit, use an $\overline{\text{INTi}}$ input low pulse width of either (1/digital filter sampling frequency × 3) or the minimum value of standard, whichever is greater.

Figure 4.10 Input Timing of External Interrupt $\overline{\text{INTi}}$ and Key Input Interrupt $\overline{\text{KIj}}$ (i = 0 to 4; j = 0 to 3)

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP64-14x14-0.80	PLQP0064GA-A	64P6U-A/—	0.7g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.32	0.37	0.42
b_1	—	0.35	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.8	—
x	—	—	0.20
y	—	—	0.10
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.3	0.5	0.7
L_1	—	1.0	—

REVISION HISTORY	R8C/36T-A Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.01	Feb 23, 2011	—	First Edition issued
1.00	Dec 09, 2011	All pages	“Preliminary”, “Under development” deleted, “sensor control unit” → “touch sensor control unit”
		2, 3	Tables 1.1 and 1.2 revised
		6	Figure 1.3 “P3_10/CH10” → “P3_1/CH10”
		11	Table 1.8 “Touch sensor control unit” added
		13	2.1 revised
		16, 17, 19 to 22, 24 to 28	Tables 3.1, 3.2, 3.4 to 3.7, 3.9 to 3.13
		32	Table 3.17 revised, Note 2 added
		33 to 56	“4. Electrical Characteristics” added

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.